Abstract

The invention relates to a method for bonding of a first substrate (1) to a second substrate (7) with the following steps, especially the following sequence:

- making contact of a first contact area (1k) of the first substrate (1) with a second contact area (18k) of the second substrate (7), which second area is aligned parallel to the first contact area (1k), as a result of which a common contact area (22) is formed,
- producing an especially spot bond interconnection between the first substrate (1) and the second substrate (7) outside the common contact area (22).

Furthermore the invention relates to a corresponding device and a substrate composite of a first substrate (1) and a second substrate (7), in which a first contact area (1k) of the first substrate (1) with a second contact area (18k) of the second substrate (7), which second area is aligned parallel to the first contact area (1k), forms a common contact area (22), outside the common contact area (22) there being an especially spot bond interconnection between the first substrate (1) and the second substrate (7).

Figure 3a in this regard